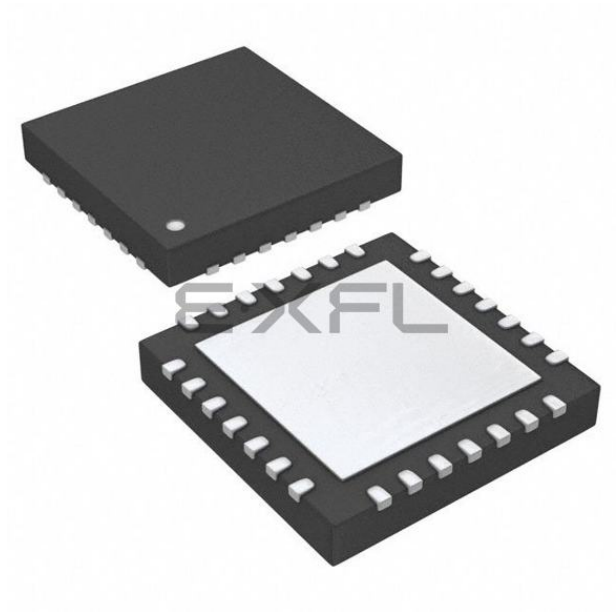


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	224 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 24x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UFQFN Exposed Pad
Supplier Device Package	28-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf15355t-i-mv

2.0 GUIDELINES FOR GETTING STARTED WITH PIC16(L)F15354/55 MICROCONTROLLERS

2.1 Basic Connection Requirements

Getting started with the PIC16(L)F15354/55 family of 8-bit microcontrollers requires attention to a minimal set of device pin connections before proceeding with development.

The following pins must always be connected:

- All VDD and VSS pins (see **Section 2.2 "Power Supply Pins"**)
- $\overline{\text{MCLR}}$ pin (see **Section 2.3 "Master Clear (MCLR) Pin"**)

These pins must also be connected if they are being used in the end application:

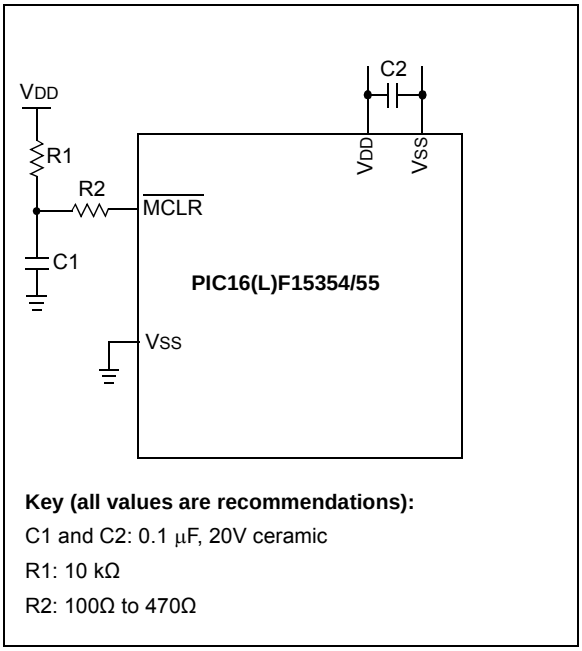
- PGC/PGD pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **Section 2.4 "ICSP™ Pins"**)
- OSCI and OSCO pins when an external oscillator source is used (see **Section 2.5 "External Oscillator Pins"**)

Additionally, the following pins may be required:

- VREF+/VREF- pins are used when external voltage reference for analog modules is implemented

The minimum mandatory connections are shown in Figure 2-1.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTIONS



Key (all values are recommendations):

C1 and C2: 0.1 μF, 20V ceramic

R1: 10 kΩ

R2: 100Ω to 470Ω

2.2 Power Supply Pins

2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins (VDD and VSS) is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A 0.1 μF (100 nF), 10-20V capacitor is recommended. The capacitor should be a low-ESR device, with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 μF in parallel with 0.001 μF).
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits, including microcontrollers, to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μF to 47 μF.

7.0 DEVICE CONFIGURATION INFORMATION

The Device Configuration Information (DCI) is a dedicated region in the Program Flash Memory mapped from 8200h to 821Fh. The data stored in the DCI memory is hard-coded into the device during manufacturing.

Refer to Table 7-1: Device Configuration Information for PIC16(L)F15354/55 Devices for the complete DCI table address and description. The DCI holds information about the device which is useful for programming and bootloader applications. These locations are read-only and cannot be erased or modified.

TABLE 7-1: DEVICE CONFIGURATION INFORMATION FOR PIC16(L)F15354/55 DEVICES

ADDRESS	Name	DESCRIPTION	VALUE		UNITS
			PIC16(L)F15354	PIC16(L)F15355	
8200h	ERSIZ	Erase Row Size	32	32	Words
8201h	WLSIZ	Number of write latches	32	32	Latches
8202h	URSIZ	Number of User Rows	128	256	Rows
8203h	EESIZ	EE Data memory size	0	0	Bytes
8204h	PCNT	Pin Count	28	28	Pins

7.1 DIA and DCI Access

The DIA and DCI data are read-only and cannot be erased or modified. See **13.3.6 "NVMREG Access to Device Information Area, Device Configuration Area, User ID, Device ID and Configuration Words"** for more information on accessing these memory locations.

Development tools, such as device programmers and debuggers, may be used to read the DIA and DCI regions, similar to the Device ID and Revision ID.

TABLE 9-3: SUMMARY OF REGISTERS ASSOCIATED WITH CLOCK SOURCES

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
OSCCON1	—	NOSC<2:0>			NDIV<3:0>				108
OSCCON2	—	COSC<2:0>			CDIV<3:0>				108
OSCCON3	CWSHOLD	SOSCPWR	—	ORDY	NOSCR	—	—	—	109
OSCFRQ	—	—	—	—	—	HFFRQ<2:0>			112
OSCSTAT	EXTOR	HFOR	MFOR	LFOR	SOR	ADOR	—	PLLR	110
OSCTUNE	—	—	HFTUN<5:0>						113
OSCEN	EXTOEN	HFOEN	MFOEN	LFOEN	SOSCEN	ADOEN	—	—	111

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by clock sources.

TABLE 9-4: SUMMARY OF CONFIGURATION WORD WITH CLOCK SOURCES

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	FCMEN	—	CSWEN	—	—	$\overline{\text{CLKOUTEN}}$	75
	7:0	—	RSTOSC<2:0>			—	FEXTOSC<2:0>			

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by clock sources.

10.3 Interrupts During Sleep

Interrupts can be used to wake from Sleep. To wake from Sleep, the peripheral must be able to operate without the system clock. The interrupt source must have the appropriate Interrupt Enable bit(s) set prior to entering Sleep.

On waking from Sleep, if the GIE bit is also set, the processor will branch to the interrupt vector. Otherwise, the processor will continue executing instructions after the SLEEP instruction. The instruction directly after the SLEEP instruction will always be executed before branching to the ISR. Refer to **Section 11.0 "Power-Saving Operation Modes"** for more details.

10.4 INT Pin

The INT pin can be used to generate an asynchronous edge-triggered interrupt. Refer to Figure 10-3. This interrupt is enabled by setting the INTE bit of the PIE0 register. The INTEDG bit of the INTCON register determines on which edge the interrupt will occur. When the INTEDG bit is set, the rising edge will cause the interrupt. When the INTEDG bit is clear, the falling edge will cause the interrupt. The INTF bit of the PIR0 register will be set when a valid edge appears on the INT pin. If the GIE and INTE bits are also set, the processor will redirect program execution to the interrupt vector.

10.5 Automatic Context Saving

Upon entering an interrupt, the return PC address is saved on the stack. Additionally, the following registers are automatically saved in the shadow registers:

- W register
- STATUS register (except for $\overline{TO}$ and $\overline{PD}$)
- BSR register
- FSR registers
- PCLATH register

Upon exiting the Interrupt Service Routine, these registers are automatically restored. Any modifications to these registers during the ISR will be lost. If modifications to any of these registers are desired, the corresponding shadow register should be modified and the value will be restored when exiting the ISR. The shadow registers are available in Bank 31 and are readable and writable. Depending on the user's application, other registers may also need to be saved.

10.6 Register Definitions: Interrupt Control

REGISTER 10-1: INTCON: INTERRUPT CONTROL REGISTER

R/W-0/0	R/W-0/0	U-0	U-0	U-0	U-0	U-0	R/W-1/1
GIE	PEIE	—	—	—	—	—	INTEDG
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **GIE:** Global Interrupt Enable bit
1 = Enables all active interrupts
0 = Disables all interrupts

bit 6 **PEIE:** Peripheral Interrupt Enable bit
1 = Enables all active peripheral interrupts
0 = Disables all peripheral interrupts

bit 5-1 **Unimplemented:** Read as '0'

bit 0 **INTEDG:** Interrupt Edge Select bit
1 = Interrupt on rising edge of INT pin
0 = Interrupt on falling edge of INT pin

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE, of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 14-3: LATA: PORTA DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-1/1	R/W-x/u	R/W-x/u	R/W-x/u
LATA7	LATA6	LATA5	LATA4	LATA3	LATA2	LATA1	LATA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **LATA<7:0>**: RA<7:0> Output Latch Value bits(1)

Note 1: Writes to PORTA are actually written to corresponding LATA register. Reads from PORTA register returns actual I/O pin values.

REGISTER 14-4: ANSELA: PORTA ANALOG SELECT REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
ANSA7	ANSA6	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **ANSA<7:0>**: Analog Select between Analog or Digital Function on pins RA<7:0>, respectively
1 = Analog input. Pin is assigned as analog input(1). Digital input buffer disabled.
0 = Digital I/O. Pin is assigned to port or digital special function.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

19.4 Minimum Operating VDD

When the temperature circuit is operated in Low range, the device may be operated at any operating voltage that is within specifications. When the temperature circuit is operated in High range, the device operating voltage, VDD, must be high enough to ensure that the temperature circuit is correctly biased.

Table 19-1 shows the recommended minimum VDD vs. Range setting.

TABLE 19-1: RECOMMENDED VDD VS. RANGE

Min.VDD, TSRNG = 1 (High Range)	Min. VDD, TSRNG = 0 (Low Range)
=> 2.5	=> 1.8

19.5 Temperature Sensor Range

The output voltage of the sensor is the highest value at -40°C and the lowest value at +125°C.

- **High Range:** The High range is used in applications with the reference for the ADC, VREF = 2.048V. This range may not be suitable for battery-powered applications.
- **Low Range:** This mode is useful in applications in which the VDD is too low for high-range operation. The VDD in this mode can be as low as 1.8V. VDD must, however, be at least 0.5V higher than the maximum sensor voltage depending on the expected low operating temperature.

19.6 DIA Information

DIA data provide ADC readings at two operating temperatures. DIA data is taken during factory testing and stored within the device. The 30°C reading alone allows single-point calibration as described in Section 19.2.1, Calibration, by solving Equation 19-1 for TOFFSET. The combined 30°C and 90°C readings allow the temperature slope Mt to be determined as well, to obtain higher accuracy in the upper-temperature range. Note that the lower- temperature range (e.g., - 40°C) will suffer in accuracy because temperature conversion must extrapolate below the reference points, amplifying any measurement errors.

Refer to **Section 6.0 "Device Information Area"** for more information on the data stored in the DIA and how to access them.

TABLE 19-2: SUMMARY OF REGISTERS ASSOCIATED WITH THE TEMPERATURE INDICATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDFVR<1:0>		ADFVR<1:0>		216
ADCON0	CHS<5:0>						GO/$\overline{\text{DONE}}$	ADON	229
ADCON1	ADFM	ADCS<2:0>			—	—	ADPREF<1:0>		230
ADACT	—	—	—	—	ADACT<3:0>				231
ADRESH	ADRESH<7:0>								232
ADRESL	ADRESL<7:0>								232

Legend: Shaded cells are unused by the Temperature Indicator module.

REGISTER 22-2: NCO1CLK: NCO1 INPUT CLOCK CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
N1PWS<2:0>(1,2)			—	N1CKS<3:0>			
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-5 **N1PWS<2:0>:** NCO1 Output Pulse Width Select bits(1)
- 111 = NCO1 output is active for 128 input clock periods
- 110 = NCO1 output is active for 64 input clock periods
- 101 = NCO1 output is active for 32 input clock periods
- 100 = NCO1 output is active for 16 input clock periods
- 011 = NCO1 output is active for 8 input clock periods
- 010 = NCO1 output is active for 4 input clock periods
- 001 = NCO1 output is active for 2 input clock periods
- 000 = NCO1 output is active for 1 input clock period

bit 4 **Unimplemented:** Read as '0'

bit 3-0 **N1CKS<3:0>:** NCO1 Clock Source Select bits
- 1011-1111 = Reserved
- 1010 = LC4_out
- 1001 = LC3_out
- 1000 = LC2_out
- 0111 = LC1_out
- 0110 = CLKR
- 0101 = SOSC
- 0100 = MFINTOSC (32 kHz)
- 0011 = MFINTOSC (500 kHz)
- 0010 = LFINTOSC
- 0001 = FINTOSC
- 0000 = FOSC

Note 1: N1PWS applies only when operating in Pulse Frequency mode.

REGISTER 23-2: CMxCON1: COMPARATOR Cx CONTROL REGISTER 1

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0
—	—	—	—	—	—	INTP	INTN
bit 7							bit 0

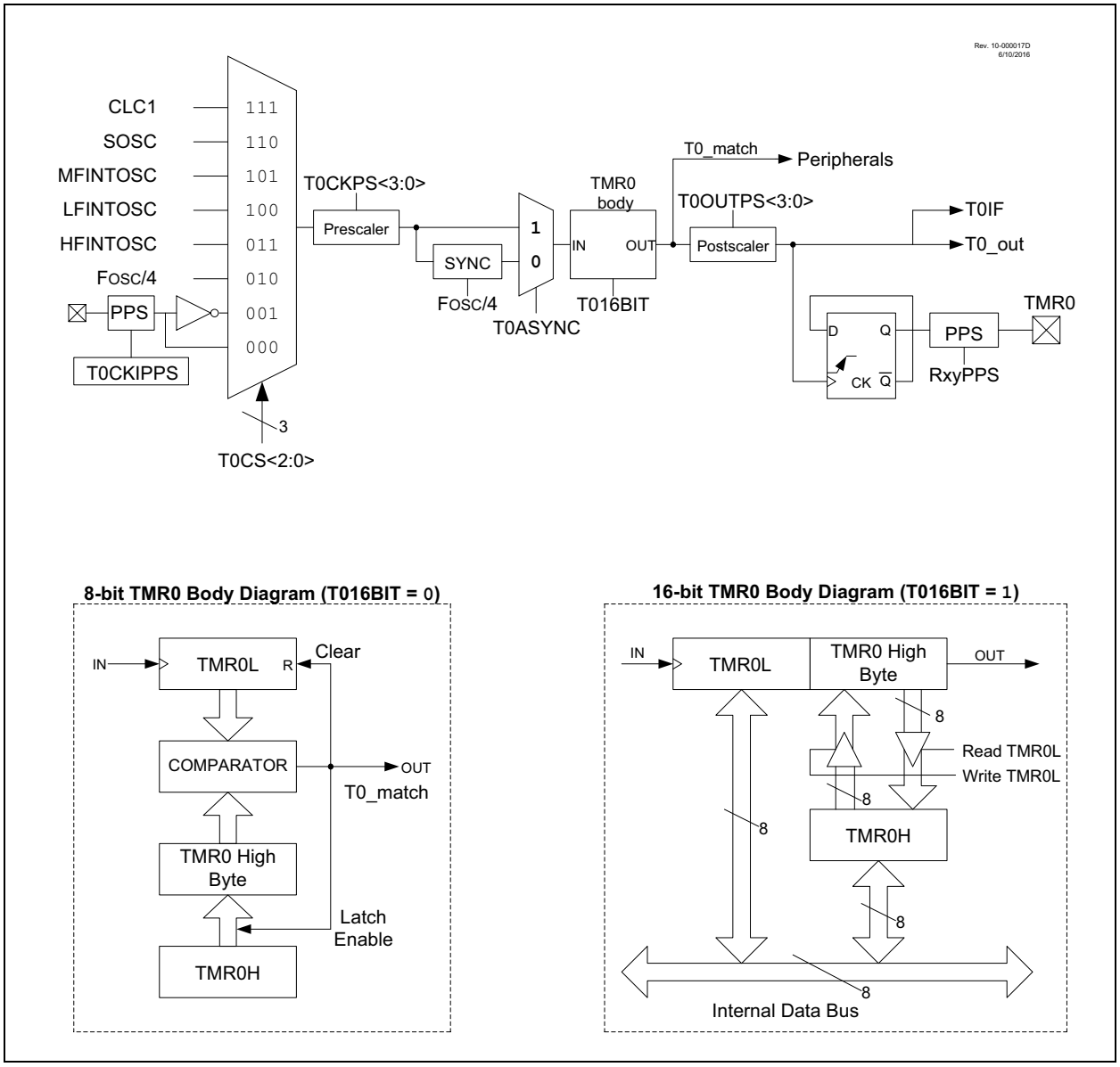
Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-2 **Unimplemented:** Read as ‘0’

bit 1 **INTP:** Comparator Interrupt on Positive-Going Edge Enable bits
1 = The CxIF interrupt flag will be set upon a positive-going edge of the CxOUT bit
0 = No interrupt flag will be set on a positive-going edge of the CxOUT bit

bit 0 **INTN:** Comparator Interrupt on Negative-Going Edge Enable bits
1 = The CxIF interrupt flag will be set upon a negative-going edge of the CxOUT bit
0 = No interrupt flag will be set on a negative-going edge of the CxOUT bit

FIGURE 25-1: BLOCK DIAGRAM OF TIMER0



REGISTER 25-2: T0CON1: TIMER0 CONTROL REGISTER 1

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
T0CS<2:0>			T0ASYNC	T0CKPS<3:0>			
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-5 **T0CS<2:0>:** Timer0 Clock Source select bits
111 = CLC1
110 = SOSC
101 = MFINTOSC (500 kHz)
100 = LFINTOSC
011 = HFINTOSC
010 = FOSC/4
001 = T0CKIPPS (Inverted)
000 = T0CKIPPS (True)

bit 4 **T0ASYNC:** TMR0 Input Asynchronization Enable bit
1 = The input to the TMR0 counter is not synchronized to system clocks
0 = The input to the TMR0 counter is synchronized to FOSC/4

bit 3-0 **T0CKPS<3:0>:** Prescaler Rate Select bit
1111 = 1:32768
1110 = 1:16384
1101 = 1:8192
1100 = 1:4096
1011 = 1:2048
1010 = 1:1024
1001 = 1:512
1000 = 1:256
0111 = 1:128
0110 = 1:64
0101 = 1:32
0100 = 1:16
0011 = 1:8
0010 = 1:4
0001 = 1:2
0000 = 1:1

28.2.1 CCPX PIN CONFIGURATION

The software must configure the CCPx pin as an output by clearing the associated TRIS bit and defining the appropriate output pin through the RxyPPS registers. See **Section 15.0 "Peripheral Pin Select (PPS) Module"** for more details.

The CCP output can also be used as an input for other peripherals.

Note:	Clearing the CCPxCON register will force the CCPx compare output latch to the default low level. This is not the PORT I/O data latch.

28.2.2 TIMER1 MODE RESOURCE

In Compare mode, Timer1 must be running in either Timer mode or Synchronized Counter mode. The compare operation may not work in Asynchronous Counter mode.

See **Section 26.0 "Timer1 Module with Gate Control"** for more information on configuring Timer1.

Note:	Clocking Timer1 from the system clock (FOSC) should not be used in Compare mode. In order for Compare mode to recognize the trigger event on the CCPx pin, TImer1 must be clocked from the instruction clock (FOSC/4) or from an external clock source.

28.2.3 AUTO-CONVERSION TRIGGER

All CCPx modes set the CCP interrupt flag (CCPxIF). When this flag is set and a match occurs, an Auto-conversion Trigger can take place if the CCP module is selected as the conversion trigger source.

Refer to **Section 20.2.5 "Auto-Conversion Trigger"** for more information.

Note:	Removing the match condition by changing the contents of the CCPRxH and CCPRxL register pair, between the clock edge that generates the Auto-conversion Trigger and the clock edge that generates the Timer1 Reset, will preclude the Reset from occurring

28.2.4 COMPARE DURING SLEEP

Since FOSC is shut down during Sleep mode, the Compare mode will not function properly during Sleep, unless the timer is running. The device will wake on interrupt (if enabled).

28.3 PWM Overview

Pulse-Width Modulation (PWM) is a scheme that provides power to a load by switching quickly between fully on and fully off states. The PWM signal resembles a square wave where the high portion of the signal is considered the on state and the low portion of the signal is considered the off state. The high portion, also known as the pulse width, can vary in time and is defined in steps. A larger number of steps applied, which lengthens the pulse width, also supplies more power to the load. Lowering the number of steps applied, which shortens the pulse width, supplies less power. The PWM period is defined as the duration of one complete cycle or the total amount of on and off time combined.

PWM resolution defines the maximum number of steps that can be present in a single PWM period. A higher resolution allows for more precise control of the pulse width time and in turn the power that is applied to the load.

The term duty cycle describes the proportion of the on time to the off time and is expressed in percentages, where 0% is fully off and 100% is fully on. A lower duty cycle corresponds to less power applied and a higher duty cycle corresponds to more power applied.

Figure 28-3 shows a typical waveform of the PWM signal.

28.3.1 STANDARD PWM OPERATION

The standard PWM mode generates a Pulse-Width Modulation (PWM) signal on the CCPx pin with up to ten bits of resolution. The period, duty cycle, and resolution are controlled by the following registers:

- PR2 registers
- T2CON registers
- CCPRxL registers
- CCPxCON registers

Figure 28-4 shows a simplified block diagram of PWM operation.

Note:	The corresponding TRIS bit must be cleared to enable the PWM output on the CCPx pin.

FIGURE 28-3: CCP PWM OUTPUT SIGNAL

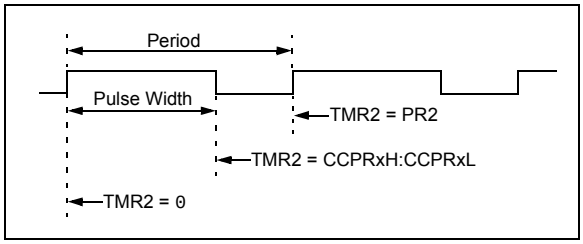


TABLE 29-3: SUMMARY OF REGISTERS ASSOCIATED WITH PWMx

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
T2CON	ON	CKPS<2:0>			OUTPS<3:0>				306
T2TMR	Holding Register for the 8-bit TMR2 Register								286*
T2PR	TMR2 Period Register								286*
RxyPPS	—	—	—	RxyPPS<4:0>					197
CWG1ISM	—	—	—	—	IS<3:0>				352
CLCxSELy	—	—	LCxDyS<5:0>						363
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	173
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	183

Legend: - = Unimplemented locations, read as '0'. Shaded cells are not used by the PWMx module.

* Page with Register information.

REGISTER 30-5: CWG1AS0: CWG1 AUTO-SHUTDOWN CONTROL REGISTER 0

R/W/HS-0/0	R/W-0/0	R/W-0/0	R/W-1/1	R/W-0/0	R/W-1/1	U-0	U-0
SHUTDOWN(1, 2)	REN	LSBD<1:0>		LSAC<1:0>		—	—
bit 7							bit 0

Legend:		
HC = Bit is cleared by hardware		HS = Bit is set by hardware
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **SHUTDOWN:** Auto-Shutdown Event Status bit(1, 2)
- 1 = An Auto-Shutdown state is in effect
- 0 = No Auto-shutdown event has occurred

bit 6 **REN:** Auto-Restart Enable bit
- 1 = Auto-restart enabled
- 0 = Auto-restart disabled

bit 5-4 **LSBD<1:0>:** CWG1B and CWG1D Auto-Shutdown State Control bits
- 11 =A logic '1' is placed on CWG1B/D when an auto-shutdown event is present
- 10 =A logic '0' is placed on CWG1B/D when an auto-shutdown event is present
- 01 =Pin is tri-stated on CWG1B/D when an auto-shutdown event is present
- 00 =The inactive state of the pin, including polarity, is placed on CWG1B/D after the required dead-band interval

bit 3-2 **LSAC<1:0>:** CWG1A and CWG1C Auto-Shutdown State Control bits
- 11 =A logic '1' is placed on CWG1A/C when an auto-shutdown event is present
- 10 =A logic '0' is placed on CWG1A/C when an auto-shutdown event is present
- 01 =Pin is tri-stated on CWG1A/C when an auto-shutdown event is present
- 00 =The inactive state of the pin, including polarity, is placed on CWG1A/C after the required dead-band interval

bit 1-0 **Unimplemented:** Read as '0'

Note 1: This bit may be written while EN = 0 (CWG1CON0 register) to place the outputs into the shutdown configuration.

2: The outputs will remain in auto-shutdown state until the next rising edge of the input signal after this bit is cleared.

REGISTER 31-9: CLCxGLS2: GATE 2 LOGIC SELECT REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LCxG3D4T	LCxG3D4N	LCxG3D3T	LCxG3D3N	LCxG3D2T	LCxG3D2N	LCxG3D1T	LCxG3D1N
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **LCxG3D4T:** Gate 2 Data 4 True (non-inverted) bit
1 = CLCIN3 (true) is gated into CLCx Gate 2
0 = CLCIN3 (true) is not gated into CLCx Gate 2

bit 6 **LCxG3D4N:** Gate 2 Data 4 Negated (inverted) bit
1 = CLCIN3 (inverted) is gated into CLCx Gate 2
0 = CLCIN3 (inverted) is not gated into CLCx Gate 2

bit 5 **LCxG3D3T:** Gate 2 Data 3 True (non-inverted) bit
1 = CLCIN2 (true) is gated into CLCx Gate 2
0 = CLCIN2 (true) is not gated into CLCx Gate 2

bit 4 **LCxG3D3N:** Gate 2 Data 3 Negated (inverted) bit
1 = CLCIN2 (inverted) is gated into CLCx Gate 2
0 = CLCIN2 (inverted) is not gated into CLCx Gate 2

bit 3 **LCxG3D2T:** Gate 2 Data 2 True (non-inverted) bit
1 = CLCIN1 (true) is gated into CLCx Gate 2
0 = CLCIN1 (true) is not gated into CLCx Gate 2

bit 2 **LCxG3D2N:** Gate 2 Data 2 Negated (inverted) bit
1 = CLCIN1 (inverted) is gated into CLCx Gate 2
0 = CLCIN1 (inverted) is not gated into CLCx Gate 2

bit 1 **LCxG3D1T:** Gate 2 Data 1 True (non-inverted) bit
1 = CLCIN0 (true) is gated into CLCx Gate 2
0 = CLCIN0 (true) is not gated into CLCx Gate 2

bit 0 **LCxG3D1N:** Gate 2 Data 1 Negated (inverted) bit
1 = CLCIN0 (inverted) is gated into CLCx Gate 2
0 = CLCIN0 (inverted) is not gated into CLCx Gate 2

The I²C interface supports the following modes and features:

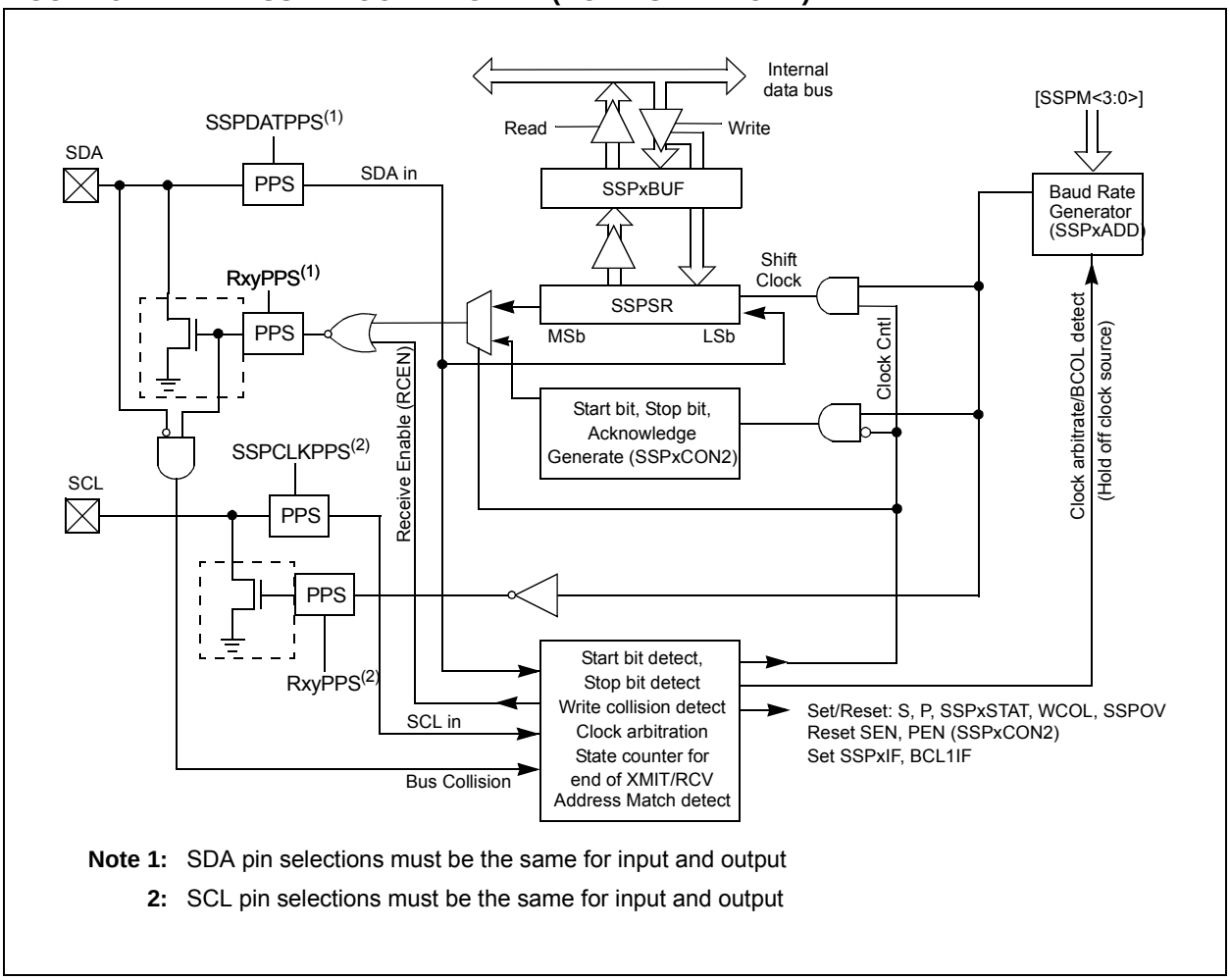
- Master mode
- Slave mode
- Byte NACKing (Slave mode)
- Limited multi-master support
- 7-bit and 10-bit addressing
- Start and Stop interrupts
- Interrupt masking
- Clock stretching
- Bus collision detection
- General call address matching
- Address masking
- Selectable SDA hold times

Figure 32-2 is a block diagram of the I²C interface module in Master mode. Figure 32-3 is a diagram of the I²C interface module in Slave mode.

Note 1: In devices with more than one MSSP module, it is very important to pay close attention to SSPxCONx register names. SSPxCON1 and SSPxCON2 registers control different operational aspects of the same module, while SSPxCON1 and SSP2CON1 control the same features for two different modules.

2: Throughout this section, generic references to an MSSPx module in any of its operating modes may be interpreted as being equally applicable to MSSPx or MSSP2. Register names, module I/O signals, and bit names may use the generic designator 'x' to indicate the use of a numeral to distinguish a particular module when required.

FIGURE 32-2: MSSP BLOCK DIAGRAM (I²C MASTER MODE)



Note 1: SDA pin selections must be the same for input and output

2: SCL pin selections must be the same for input and output

TABLE 36-3: INSTRUCTION SET (CONTINUED)

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb LSb	Status Affected	Notes
CONTROL OPERATIONS						
BRA	k	Relative Branch	2	11 001k kkkk kkkk		
BRW	–	Relative Branch with W	2	00 0000 0000 1011		
CALL	k	Call Subroutine	2	10 0kkk kkkk kkkk		
CALLW	–	Call Subroutine with W	2	00 0000 0000 1010		
GOTO	k	Go to address	2	10 1kkk kkkk kkkk		
RETFIE	k	Return from interrupt	2	00 0000 0000 1001		
RETLW	k	Return with literal in W	2	11 0100 kkkk kkkk		
RETURN	–	Return from Subroutine	2	00 0000 0000 1000		
INHERENT OPERATIONS						
CLRWDT	–	Clear Watchdog Timer	1	00 0000 0110 0100	$\overline{TO}$, $\overline{PD}$	
NOP	–	No Operation	1	00 0000 0000 0000		
RESET	–	Software device Reset	1	00 0000 0000 0001		
SLEEP	–	Go into Standby or IDLE mode	1	00 0000 0110 0011	$\overline{TO}$, $\overline{PD}$	
TRIS	f	Load TRIS register with W	1	00 0000 0110 0fff		
C-COMPILER OPTIMIZED						
ADDFSR	n, k	Add Literal k to FSRn	1	11 0001 0nkk kkkk		
MOVIW	n mm	Move Indirect FSRn to W with pre/post inc/dec modifier, mm	1	00 0000 0001 0nmm	Z	**2, 3**
	k[n]	Move INDFn to W, Indexed Indirect.	1	11 1111 0nkk kkkk	Z	**2**
MOVWI	n mm	Move W to Indirect FSRn with pre/post inc/dec modifier, mm	1	00 0000 0001 1nmm		**2, 3**
	k[n]	Move W to INDFn, Indexed Indirect.	1	11 1111 1nkk kkkk		**2**

Note 1: If the Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

2: If this instruction addresses an INDF register and the MSb of the corresponding FSR is set, this instruction will require one additional instruction cycle.

3: See Table in the MOVIW and MOVWI instruction descriptions.

37.3 DC Characteristics

TABLE 37-1: SUPPLY VOLTAGE

PIC16LF15354/55			Standard Operating Conditions (unless otherwise stated)				
PIC16F15354/55							
Param. No.	Sym.	Characteristic	Min.	Typ.†	Max.	Units	Conditions
Supply Voltage							
D002	VDD		1.8 2.5	— —	3.6 3.6	V V	FOSC ≤ 16 MHz FOSC > 16 MHz
D002	VDD		2.3 2.5	— —	5.5 5.5	V V	FOSC ≤ 16 MHz FOSC ≥ 16 MHz
RAM Data Retention(1)							
D003	VDR		1.5	—	—	V	Device in Sleep mode
D003	VDR		1.7	—	—	V	Device in Sleep mode
Power-on Reset Release Voltage(2)							
D004	VPOR		—	1.6	—	V	BOR or LPBOR disabled(3)
D004	VPOR		—	1.6	—	V	BOR or LPBOR disabled(3)
Power-on Reset Rearm Voltage(2)							
D005	VPORR		—	0.8	—	V	BOR or LPBOR disabled(3)
D005	VPORR		—	1.5	—	V	BOR or LPBOR disabled(3)
VDD Rise Rate to ensure internal Power-on Reset signal(2)							
D006	SVDD		0.05	—	—	V/ms	BOR or LPBOR disabled(3)
D006	SVDD		0.05	—	—	V/ms	BOR or LPBOR disabled(3)

† Data in "Typ." column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: See Figure 37-3, POR and POR REARM with Slow Rising VDD.

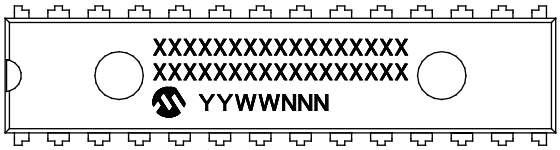
3: Please see Table 37-11 for BOR and LPBOR trip point information.

4: = LF device

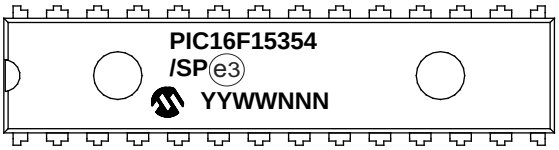
40.0 PACKAGING INFORMATION

40.1 Package Marking Information

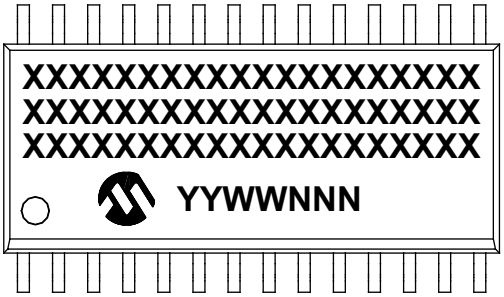
28-Lead SPDIP (.300”)



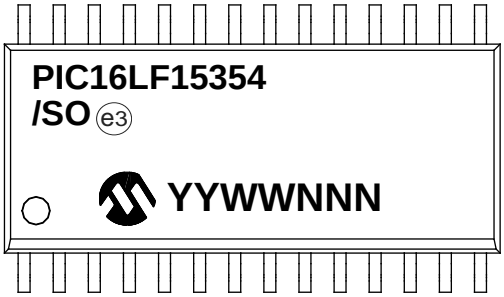
Example



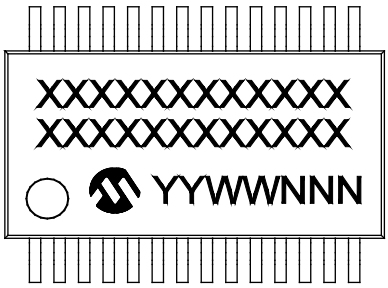
28-Lead SOIC (7.50 mm)



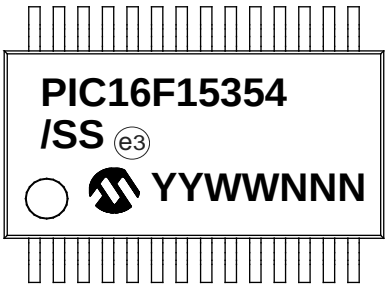
Example



28-Lead SSOP (5.30 mm)



Example

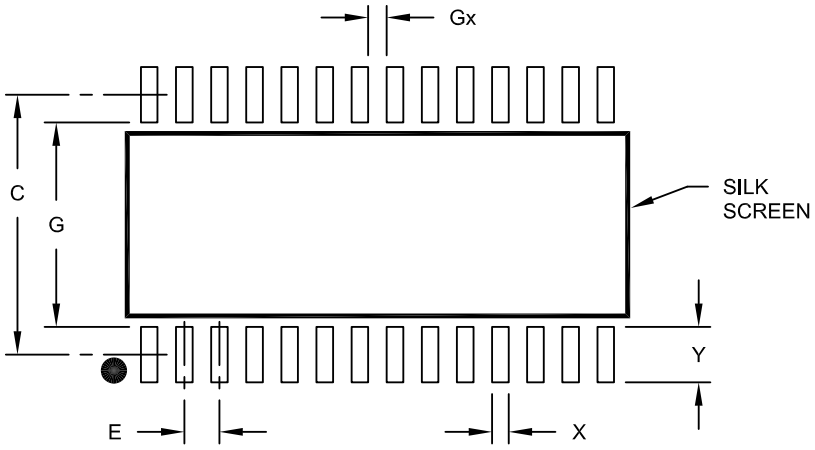


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A